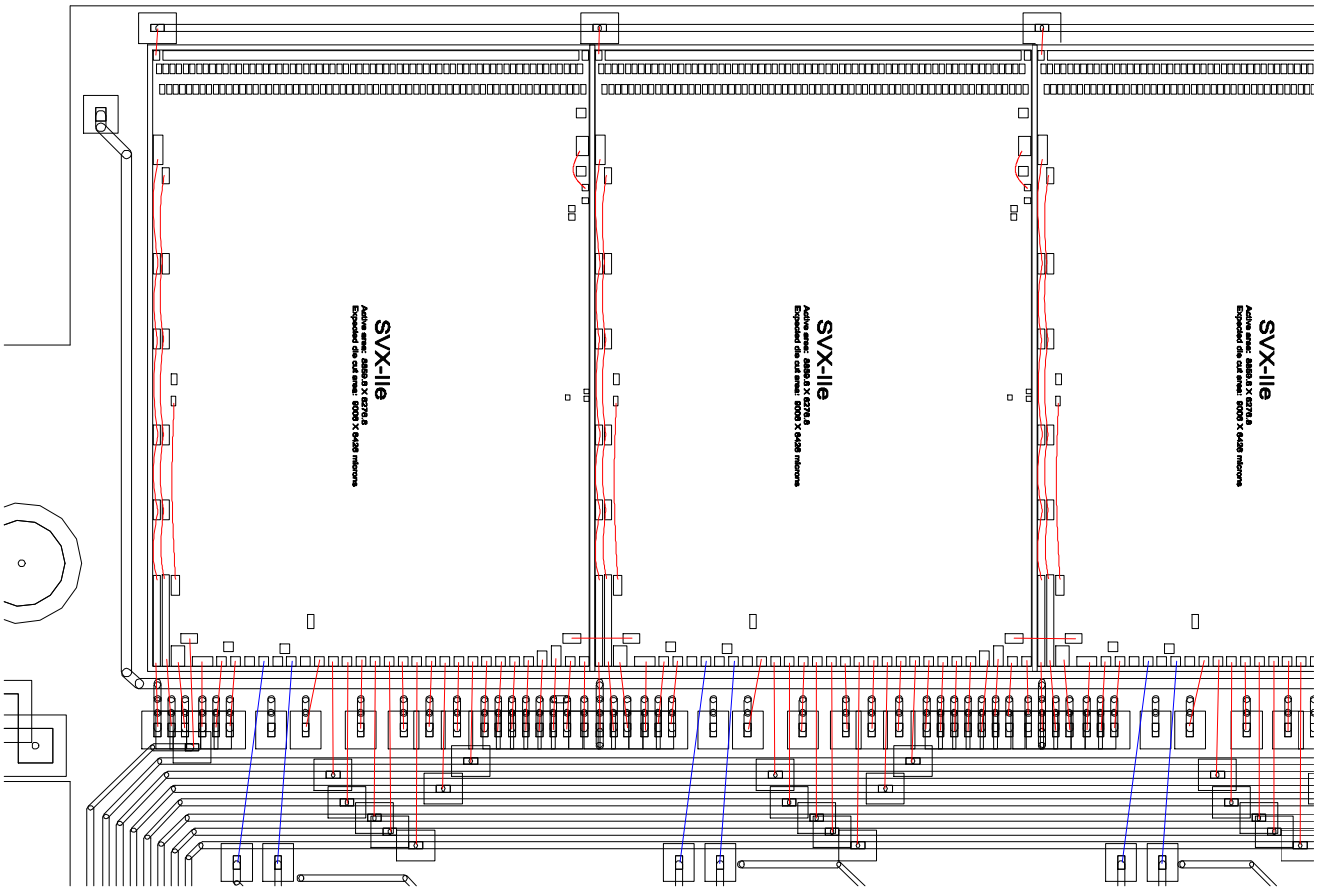
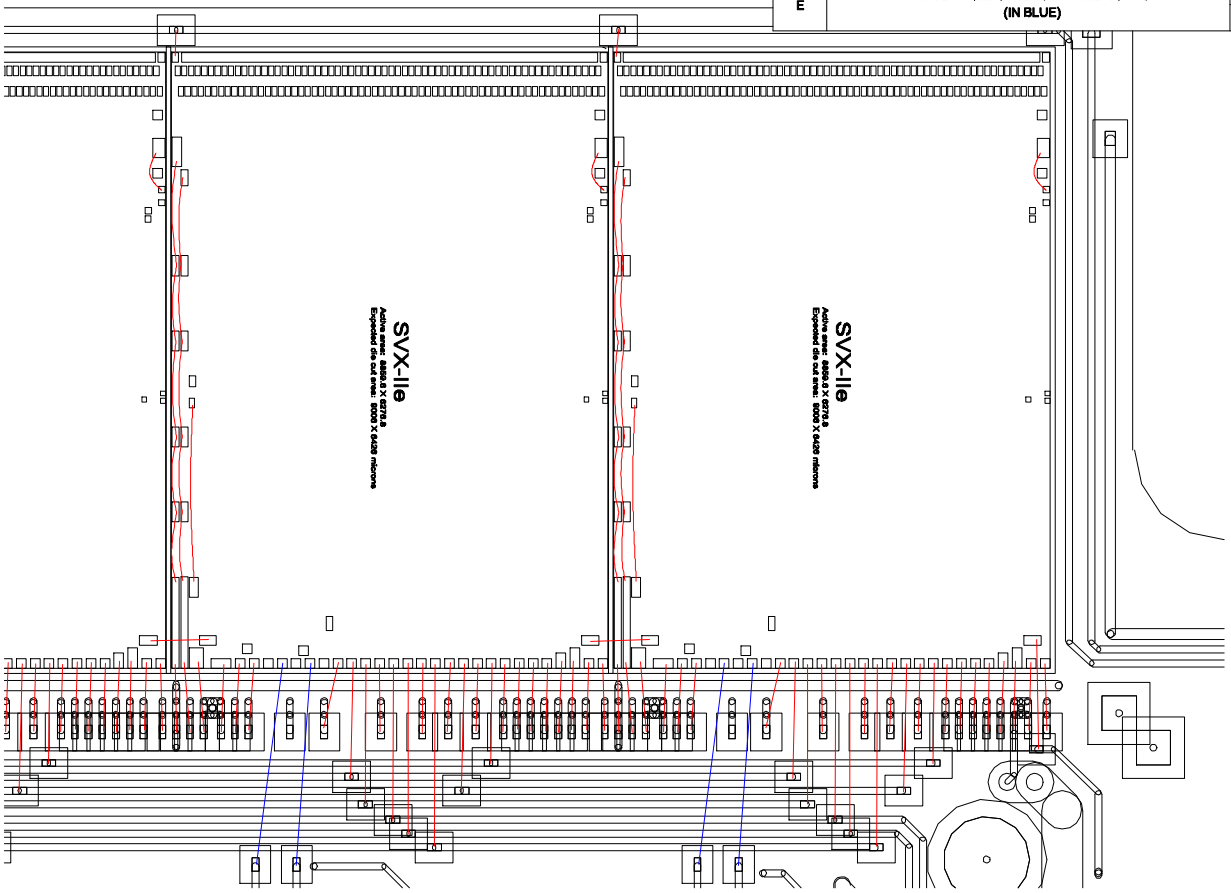

SVX-IIe
Active area: 8889.0 X 6278.0
Expanded die cut area: 9000 X 6438 microns
SVX-IIe
Active area: 8889.0 X 6278.0
Expanded die cut area: 9000 X 6438 microns
SVX-IIe
Active area: 8889.0 X 6278.0
Expanded die cut area: 9000 X 6438 microns

REV.	DESCRIPTION	DRAWN / APPD.	DATE / DATE
C	INDICATE POSITION OF 4 CIRCUIT CORRECTION WIRE BONDS (IN GREEN)	MATULIK	02/04/99
D	CORRECTED TO REPRESENT HDI 3954	MATULIK	03/11/99
E	ADDED PULL STRENGTH WIRE BONDS (IN BLUE)	MATULIK	01/11/00



ITEM	PART NUMBER	DESCRIPTION OR SIZE	QTY
PARTS LIST			

UNLESS OTHERWISE SPEC.			ORIGINATOR	M. Matulik	09/08/98
RADII	DECIMALS		DRAWN BY	M. Matulik	09/08/98
0.030	0.005		CHECKED BY		
DIMENSIONS IN INCHES.			APPROVED BY		
			USED ON -		
			MATERIAL -		

FERMI NATIONAL ACCELERATOR LABORATORY
UNITED STATES DEPARTMENT OF ENERGY

HIGH DENSITY INTERCONNECT
9 CHIP BARREL HDI
BONDING DIAGRAM

SCALE	FILMED	DRAWING NUMBER	Sheet 2 of 2	REV.
		3823.112-MB-330190		E